APPLICA	BLE STA	NDARD										
Operating temperature ra		e range	-55 °C to 85 °C	С	range	temperature			-10°C TO 50°C(Packed condition		on)	
RATING	Voltage		30V AC/DC		humidit	.y range		Re	elative humidity 90 % MAX	(Not d	ewed)	
Current			0.25 A Appl			cable cable t=0.3±0.03mm, Gold			plating	g		
			SPEC	IFICA	10IT/	NS						
IT	EM		TEST METHOD				F	EQU	IREMENTS	QT	АТ	
CONSTR		 J	1201 11100				<u> </u>			Ι α.	7	
General exa			and by measuring instrumer	nt.		According to drawing.			×	×		
Marking		Confirme	Confirmed visually.			(note 1)			×	×		
ELECTR	ICAL CH	ARACTE	RISTICS							1	l .	
Voltage proof			for 1 min.			No flashover or breakdown.				×	×	
Insulation resistance		100 V DC	100 V DC.			50 MΩ MIN.				×	×	
Contact resis	stance	AC 20 m	V MAX , 1 mA .			100 mΩ MAX.				×	×	
Cornact resid	Janoo	7.0 20 111	AO 20 IIIV WAX , TIIIA .					sulk r	esistance (L=8mm)	^	^	
MECHAN			ERISTICS			includi	ily FFC I	ouik i	esistance (L=onini)			
Vibration	HOAL OF		cy 10 to 55 Hz, half amplitude	de		① No	electrica	l disc	ontinuity of 1 μs.	×	I _	
		0.75 mm	0.75 mm, for 10 cycles in 3 axial directions.						e: 100 mΩ MAX.			
Shock			981 m/s <sup>2</sup> , duration of pulse 6 ms			③ No	damage	crac	k and looseness of parts.	×	_	
Mechanical of	peration		at 3 times in 3 both axial directions.  10 times insertions and extractions.			① Contact resistance: 100 mΩ MAX.			×	<u> </u>		
				-		② No damage, crack and looseness of parts.			^			
FPC insertio	n force		Measured by applicable FPC				Insertion force : Direction of insertion			×	_	
			ss of FPC shall be t=0.30mr	m		2.6+0.14 × n N MAX ( <i>note 2</i> )						
FPC retentio	n force		at initial condition.)  Measured by applicable FPC				(n: Number of contacts)  Retention force : Direction of extraction				<del> </del>	
		(Thicknes	(Thickness of FPC shall be t=0.30mm				×n N M			×		
			condition.)			(n: Nur	mber of c	ontac	ets)			
			ACTERISTICS							•		
Corrosion sa	lt mist	Exposed for 96 h.	at $35\pm2$ °C, $5$ % salt wate	r spray		① Contact resistance: 100 mΩ MAX.				×	_	
Rapid chang	e of		ture-55→+15⊤0+35→+85≕	÷+15⊤∩+3	5°C	① Contact resistance: 100 mΩ MAX.				×	<del>  _  </del>	
temperature		Time	l ·			<ul><li>Insulation resistance: 50 MΩ MIN.</li></ul>						
			Under 5 cycles.			③ No damage, crack and looseness of parts.						
Damp heat (steady state	<u>.)</u>		Exposed at 40±2 °C, Relative humidity 90 to 95 %, 96 h.							×	_	
Damp heat,c	•		Exposed at -10 to +65 °c,			(1) Cor	ntact resi	stanc	e: 100 mΩ MAX.	×	_	
,	•	Relative	Relative humidity 90 to 96 %, 10 cycles, TOTAL 240 h.			<ul> <li>② Insulation resistance: 1 MΩ MIN.         (At high humidity)</li> <li>③ Insulation resistance: 50 MΩ MIN.         (At dry)</li> <li>④ No damage, crack and looseness of parts</li> </ul>						
		10 cycles										
COUN	т	DESCRIPTION	ON OF REVISIONS		DESIG	NED			CHECKED		L ATE	
<b>A</b>	<u>'</u>	DEGORII TI	SIV OF REVIOIONO		DEGIG	INLD			OFICORED	<i>D</i>	DATE	
REMARK							APPRO	VED	NF. MIYAZAKI	17. 0	08. 23	
						CHECK				1	08. 23	
						DESIGNE		NED	HH. MURAKAMI		08. 23	
Unless otherwise specified, refer			er to IEC 60512.			DRAWN		VN	HH. MURAKAMI	17. 08. 23		
Note QT:Qualification Test AT:Assurance Test X:Applicable Test				DR	PRAWING NO. ELC-368163-		9-00	0				
שכ		SPECIFI	PECIFICATION SHEET			NO. FI		FH6	H62-**S-0. 25SHW(99			
$\pi$			OSE ELECTRIC CO., LTD.			CODE NO.				Δ	1/2	
FORM HD0011_2_1			332 EEE31110 33., E13.				ULJOU		<del>~~</del>			

SPECIFICATIONS								
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ				
Dry heat	Exposed at 85±2°C, 96 h.	① Contact resistance: 100 mΩ MAX.	×	_				
Cold	Exposed at -55±3°C, 96 h.	② No damage, crack and looseness of parts	×	_				
Sulphur dioxide [JIS C 60068-2-42]	Exposed at $40\pm2$ °C, Relative humidity $80\pm5\%$ $25\pm5$ ppm for 96 h.	① Contact resistance: 100 mΩ MAX.	×	-				
Hydrogen sulphide [JIS C 60068-2-43]	Exposed at $40\pm2$ °C, Relative humidity $80\pm5\%$ , 10 to 15 ppm for 96 h.		×					
Solderability	Soldered at solder temperature, 245±3°C for immersion duration,3±0.3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	Ι				
Resistance to soldering heat	1) Reflow soldering: Peak TMP. 250 °C MAX. Reflow TMP. over 220 °C 60 to 90 sec. Number of reflow: 2 times 2) Soldering irons: TMP. 350±10 °C for 5±1 sec.	No deformation of case of excessive looseness of the terminals. ( <i>note 4</i> )	×					

## (note 1)

This product features top-contact point.

"One Action Lock" completes FPC lock just by inserting the FPC.

Do not operate the locking-lever when inserting the FPC.

## (note 2)

Do not insert the FPC to this product at an angle.

## (note 3)

Stabilize the FPC to PCB or something fixed, if pull-up or pull-down force is exepected to be applied to the FPC.

## (note 4)

Blisters which may be generated on the housing do not affect product performance.

Note QT:Q	ualification Test AT:Assurance Test X:Applicable Test	DRAWIN	IG NO.	ELC-368163-99-00		
HS	SPECIFICATION SHEET	PART NO.	FH62-**S-0. 25SHW(99)			
	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	Δ	2/2